

FEATURES

- Transient surge voltage protection.
- Diffused-junction. Glass passivated and encapsulated.

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

Items	Ту	ре	U17B	U17C	U17D	U17E				
Repetitive Peak Reverse Voltage	V _{RRM}	V	100	200	300	400				
Peak Reverse Power	P _{RM}	kW	3(Tj = 25°C, Impulse duration 10μs Non-repetitive)							
Average Forward Current	I _{F(AV)}	А	2.5 (Single-phase half sine wave 180° conduction $T_L=90$ °C, Lead length = 10mm							
Surge(Non-Repetitive) Forward Current	I _{FSM}	А	100(Without PIV, 10ms conduction, Tj = 175°C start							
I ² t Limit Value	l ² t	A ² s	40(Time = 2 ~ 10ms, I = RMS value)							
Operating Junction Temperature	Tj	°C	-40 ~ +175							
Storage Temperature	T _{stg}	°C								

Notes (1) Lead mounting : Lead temperature 300°C max. to 3.2mm from body for 5sec. max.

(2) Mechanical strength : Bending 90°×2 cycles or 180°×1 cycle, Tensile 3kg, Twist 90°×1 cycle.

CHARACTERISTICS(T_L=25°C)

Items	Symbols	ymbols Units Min. Typ. Max.			Test Co	Test Conditions		
		μΑ	-	4	50	B class		
Peak Reverse Current	I _{RRM}			1.5	20	C,D class	Rated V_{RRM}	
				0.6	10 E class			
Peak Forward Voltage	V_{FM}	V	_	_	1.1	I _{FM} =2.5Ap, Single wave 1 cycle	-phase half sine	
Reverse Recovery Time	trr	μs	-	3.0	-	$I_F=2mA$, $V_R=-15V$		
Avalanche Voltage	alanche Voltage V _{AVL} V Ta				d 2	I_{RM} =1.0mA, Single-phase half sine wave 1 pps, Time $\leq 5s$		
Avalanche Voltage Temperature Coefficient	α	%/°C	_	0.080	_	$\frac{\Delta VAVL}{VAVL} \times \frac{1}{175-25}$	×100	
Steady State Thermal Impedance	R _{th(j-a)} R _{th(j-l)}	°C/W	_	_	60 30	Lead length = 10	mm	



U17

TABLE.1 Standard voltage

V _{RRM} Class	E	3	([)	E	Units V		
V _{AVL}	MIN. MAX. 230 415		MIN.	MAX.	MIN.	MAX.	MIN.		MAX.	
Band			280	505	375	725	465		805	
"example order type" U17C V _{RRM} : 200V / IF _(AV) : 2.5A / V _{AVL} : 280~505V										

TABLE.2 Optional voltage : for Large order products

V	RRM Clas	s		E	3		С			D					Linita			
VA	vL Symb	ols	27	30	33	36	33	36	39	44	44	50	55	63	55	63	70	Units
Г	TYP. VAV	1	270	300	330	360	330	360	390	440	440	500	550	630	550	630	700	V
	Α	MIN	230	255	280	305	280	305	330	375	375	425	465	535	465	535	595	
V_{AVL}	±15%	MAX	310	345	380	415	380	415	450	505	505	575	635	725	635	725	805	v
Band	В	MIN	250	280	305	330	305	330	360	405	405	460	505	580	505	580	645	v
	±7.5%	MAX	290	320	355	390	355	390	420	475	475	535	590	680	590	680	750	

"example order type" U17C36A

 $V_{RRM}: 200V \ / \ IF_{(AV)}: 2.5A \ / \ V_{AVL}: 305{\sim}415V$

Forward characteristics







Max. average forward power dissipation (Resistive or inductive load)



Max. allowable lead temperature (Resistive or inductive load)



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U17

Surge forward current characteristics (Non-repetitive)



Steady-state thermal impedance







Typ. Reverse current vs. junction temperature



Transient thermal impedance



Reverse recovery time (trr) test circuit



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Precautions for Safe Use and Notices

If semiconductor devices are handled inappropriate manner, failures may result. For this reason, be sure to read "Precaution for Use" before use.



This mark indicates an item about which caution is required.

CAUTION This mark indicates a potentially hazardous situation which, if not avoided, may result in minor or moderate injury and damage to property.

\triangle CAUTION

- (1) Regardless of changes in external conditions during use "absolute maximum ratings" should never be exceed in designing electronic circuits that employ semiconductors. In the case of pulse use, furthermore, "safe operating area(SOA)" precautions should be observed.
- (2) Semiconductor devices may experience failures due to accident or unexpected surge voltages. Accordingly, adopt safe design features, such as redundancy or prevention of erroneous action, to avoid extensive damage in the event of a failure.
- (3) In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, life-support-related medical equipment, fuel control equipment and various kinds of safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of user's fail-safe precautions or other arrangement. Or consult Hitachi's sales department staff.

(If a semiconductor device fails, there may be cases in which the semiconductor device, wiring or wiring pattern will emit smoke or cause a fire or in which the semiconductor device will burst)

NOTICES

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